



**【1. 適用範圍 SCOPE】**

此種規格包括 PH2.0mm Pitch SMT & DIP 連接器系列

This Specification Covers the PH2.0mm Pitch DIP & SMT Connector Series.

**【2. 规格与料号 Spec and Part number】**

规格内容 / Specification		产品料号 / Production No.
端子 / Terminal		A2001-XXX
胶壳 / Housing		A2001H-NP
針座 / Wafer	90 度 / Right Angle	A2001WR/WV-NP A2001WR/WV-S-NP
	180 度 / Straight	

**【3. 材质与表面处理 Disposal of Material and surface】**

规格内容 / Specification		材质 / Materials	表面处理 / Disposal of Surface
端子 / Terminal		黄铜 / Barss 磷铜 / Phosphor Bronze	Plating Before Stamping -Sn: 40 μ" or 60 μ" Plating Before Stamping -Ni: 10 μ" or 30 μ" Stamping Before Plating -Sn: 70 μ" or 120 μ" Stamping Before Plating -Ni: 30 μ" or 50 μ" Gold Flash: 1 μ" or 3 μ"
胶壳 / Housing		尼龙 66 / Nylon 66	UL 94V-0
針座 / Wafer	Base	Nylon 66 + 15%GF Nylon 66 + 30%GF Or PA 6T	UL 94V-0
	PIN	黄铜 / Brass	Tin 70 μ" Plated (亮锡 / 雾锡) Over 30 μ" Nickel

(上述参数请以工程图为准 / Please Refer to the Project drawing for the above Specification)

**【4. 额定等级 Ratings and applicable wires】**

項目【Item】	规格【Standard】	
额定电压 Rated Voltage (Max.)	100V	[AC/DC]
额定电流 Rated Current (Max.)	2A	
使用温度范围 Ambient temperature Range	-40°C ~ +105°C	
适用线径 Applicable wire insulation O.D	AWG24#、26#、28#、30# Insulation O. D. 1.50mm(Max.)	

\*升温時含端子. Including terminal temperature rise.

<b>A/1</b>	<b>NEW</b>	<b>TITLE:</b> PH2.0mm Pitch Connector Series			<b>Sheet: 1 of 8</b>
	<b>REV.</b>	<b>DESCRIPTION</b>	<b>WRITTEN BY:</b> Liu jun	<b>CHECKED BY:</b> K B. Sun	<b>APPROVED BY:</b> Succeed. Sun

**【5. 性能 PERFORMANCE】**

**5-1. 電氣的性能 Electrical Performance.**

項 目 【Item】		條 件 【Test Condition】	規 格 【Requirement】
5-1-1	接觸阻抗 Contact Resistance	公母配合, 開放電壓 20mV 以下, 電流 10mA 檢測連接器. Mate connectors, measure by dry circuit, 20mV MAX, 10mA. (Based upon EIA-364-06A).	20 milliohms Max.
5-1-2	絕緣阻抗 Insulation Resistance	公母配合, 在相鄰端子, 端子與地片之間, 使用 500V 的直流電, 檢測連接器. Mate connectors, apply 500V DC between adjacent terminal or ground. (Based upon EIA-364-21B / MIL-STD-202 Method 302 Cond. B)	1000 Megohms Min.
5-1-3	耐電壓 Dielectric Strength	公母配合, 在相鄰端子, 端子與地片之間, 使用 800V 的交流電 1 分鐘, 檢測連接器. Mate connectors, apply 800V AC for 1 minute between adjacent terminal or ground. (Based upon EIA-364-20A / MIL-STD-202 Method 301)	不出現中斷等情況 No Breakdown and Flashover
5-1-4	铆线后端子接觸阻抗 Contact resistance on crimped portion	铆线后之端子, 開放電壓 20mV 以下, 電流 10mA 檢測連接器. Crimp the applicable wire on to the terminal measure by dry circuit 20mV MAX, 10mA.	10 milliohms Max.

**5-2. 機械的性能 Mechanical Performance.**

<b>A/1</b>	<b>NEW</b>	<b>TITLE:</b> PH2. 0mm Pitch Connector Series			<b>Sheet: 2 of 8</b>
<b>REV.</b>	<b>DESCRIPTION</b>	<b>WRITTEN BY:</b> <b>Liu jun</b>	<b>CHECKED BY:</b> <b>K B. Sun</b>	<b>APPROVED BY:</b> <b>Succeed. Sun</b>	<b>DATE: YR/MO/DAY</b> <b>2017/06/25</b>



	項 目 【Item】	條 件 【Test Condition】	規 格 【Requirement】						
5-2-1	插拔力 Insertion and Withdrawal Force	以每分鍾 25±3mm 的速率插入和拔出。 Insert and withdraw connectors at the speed rate of 25±3mm/minute.	參照第 6 項 Refer to paragraph 6						
5-2-2	端子保持力 Terminal/ Housing Retention Force	以每分 25±3mm 的速率, 將端子從 Housing 內軸向拔出的力量。 Apply axial pull out force at the speed rate of 25±3mm/minute on the terminal assembled in the housing.	14.7N {1.5kgf} Min.						
5-2-3	端子插入力 Terminal Insertion Force	鉚線后之端子插入 Housing 所需最大力 量。 Insert the crimped terminal into the housing.	9.8N {1.0kgf} Max.						
5-2-4	SMT Pin 針保持力 SMT Pin Retention Force	以每分 25±3mm 的速率, 將 PIN 針從 Wafer 內軸向拔出的力量。 Apply axial push force at the speed rate of 25±mm/minute.	4.9N {0.5kgf} Min.						
	DIP Pin 針保持力 DIP Pin Retention Force	以每分 25±3mm 的速率, 將 PIN 針從 Wafer 內軸向拔出的力量。 Apply axial push force at the speed rate of 25±mm/minute.	5.88N {0.6kgf} Min.						
5-2-5	端子壓着強度 Tensile strength (Crimped connections)	固定鉚線后的端子, 使電線與端子分離時 所需的最小力量。 Fix the crimped terminal, apply axial pull out force on the wire. (Do not crimp insulation part).	AWG#	#30	#28	#26	#24		
			Spec. kgf Min.	0.8	1.0	2.0	3.0		
			Note> As for unspecified wire sizes in this specification define values with clients						

<b>A/1</b>	<b>NEW</b>	<b>TITLE:</b> PH2.0mm Pitch Connector Series			<b>Sheet: 3 of 8</b>
<b>REV.</b>	<b>DESCRIPTION</b>	<b>WRITTEN BY:</b> Liu jun	<b>CHECKED BY:</b> K B. Sun	<b>APPROVED BY:</b> Succeed. Sun	<b>DATE: YR/MO/DAY</b> 2017/06/25



**5-3. 環境性能及其它 Environmental Performance and Others.**

項目 【Item】		條件 【Test Condition】	規格 【Requirement】	
5-3-1	重復插拔 Repeated Insertion/ Withdrawal	以每分鐘不超過 10 次的速率, 將公母插拔 50 次. When mated up to 50 cycles repeatedly by the rate of 10 cycles per minute.	接觸阻抗 Contact Resistance	20 milliohms Max.
5-3-2	溫升測試 Temperature Rise	公母對插後, 在通過額定電流下, 所測定的溫度. Carrying rated current load. (UL 1997)	溫升測試 Temperature rise	30°C Max.
5-3-3	耐振動性 Vibration	振幅: 1.5mm P-P 時間: 10~55~10 HZ in 1 minute 持續時間: 每軸向 2 小時 Amplitude: 1.5mm P-P Sweep time: 10~55~10 HZ in 1 minute Duration: 2 hours in each X.Y.Z axials. (Based upon EIA-364-28B/MIL-STD-202 Method 213B Cond. A)	外觀 Appearance	無異狀 No Damage
			接觸阻抗 Contact Resistance	20 milliohms Max.
			瞬斷 Discontinuity	1 micro-second Max.
5-3-4	耐沖擊性 Shock	在 X.Y.Z 上 6 個方向上, 以 490m/s <sup>2</sup> (50g 的力量)各擊下. 490m/s <sup>2</sup> {50G}, 3 strokes in each X.Y.Z. axes. (Based upon EIA-364-27B/MIL-STD-202 Method 213B Cond. A)	外觀 Appearance	無異狀 No Damage
			接觸阻抗 Contact Resistance	20 milliohms Max.
			瞬斷 Discontinuity	1 micro-second Max.
5-3-5	耐熱性 Heat Resistance	85±2°C, 96 hours. (Based upon MIL-STD-202 Method 108A Cond. A)	外觀 Appearance	無異狀 No Damage
			接觸阻抗 Contact Resistance	20 milliohms Max.

<b>A/1</b>	<b>NEW</b>	<b>TITLE:</b> PH2.0mm Pitch Connector Series			<b>Sheet: 4 of 8</b>
		<b>WRITTEN BY:</b> Liu jun	<b>CHECKED BY:</b> K B. Sun	<b>APPROVED BY:</b> Succeed. Sun	
<b>REV.</b>	<b>DESCRIPTION</b>	<b>DATE: YR/MO/DAY</b> 2017/06/25			



項 目 【Item】		條 件 【Test Condition】	規 格 【Requirement】	
5-3-6	耐寒性 Cold Resistance	-25 ± 5 °C , 96 hours. ( Based upon EIA-364-105)	外觀 Appearance	無異狀 No Damage
			接觸阻抗 Contact Resistance	20 milliohms Max.
5-3-7	耐濕性 Humidity	溫度: 40±2°C 濕度: 90~95%(RH) 持續時間: 96 hours Temperature: 40±2°C Relative Humidity: 90~95% Duration: 96 hours (Based upon EIA-364-31A/MIL-STD-202 Method 103B Cond. B)	外觀 Appearance	無異狀 No Damage
			接觸阻抗 Contact Resistance	20 milliohms Max.
			耐電壓 Dielectric Strength	Must meet 5-1-3
			絕緣阻抗 Insulation Resistance	100 Megohms MIN
5-3-8	溫度變化 Temperature Cycling	從-55°C持續 30 分鍾升至+85°C持續 30 分 鍾, 循環 5 次. 5 cycles of: a) -55°C 30 minutes. b) +85°C 30 minutes. (Based upon EIA-364-32B)	外觀 Appearance	無異狀 No Damage
			接觸阻抗 Contact Resistance	20 milliohms Max.
5-3-9	鹽水噴霧 Salt Spray	在溫度 35±2°C, 鹽水濃度 5±1%下, 鹽水噴 霧 12±1 小時. 12±1 hours exposure to a salt spray from the 5 ± 1% solution at 35 ± 2 °C . (Based upon EIA-364-26A/MIL-STD-202 Method 101D Cond. B).	外觀 Appearance	無異狀 No Damage
			接觸阻抗 Contact Resistance	20 milliohms Max.

<b>A/1</b>	<b>NEW</b>	<b>TITLE:</b> PH2. 0mm Pitch Connector Series			<b>Sheet: 5 of 8</b>
<b>REV.</b>	<b>DESCRIPTION</b>	<b>WRITTEN BY:</b> Liu jun	<b>CHECKED BY:</b> K B. Sun	<b>APPROVED BY:</b> Succeed. Sun	<b>DATE: YR/MO/DAY</b> 2017/06/25



項 目 【Item】		條 件 【Test Condition】	規 格 【Requirement】	
5-3-10	焊錫附著性 Solder-ability	焊接時間: 3±0.5 秒. 焊接溫度: 250±5°C. Soldering Time: 3±0.5second. Solder Temperature: 250±5°C. (Based upon EIA-364-52)	Solder Wetting	浸漬面積需 95%以上 95% of immersed area must show no voids, pin holes.
5-3-11	DIP 焊錫耐熱性 DIP Solder-Resistance	焊接時間: 5±1 秒(自動焊). 焊接溫度: 255±5°C. 焊接時間: 3±1 秒(手工焊). 焊接溫度: 350±5°C. Soldering time:5±1sec solder. Temperature:255 ± 5 °C (Automatic soldering). Soldering time:3±1sec solder. Temperature:350 ± 5 °C . (Manual soldering) (Based upon EIA-364-56A)	外觀 Appearance	無異狀 No Damage
5-3-12	SMT 焊錫耐熱性 SMT Solder-Resistance	焊接時間: 5±1 秒. 焊接溫度: 260±5°C. Soldering time:5±1sec solder. Temperature:260±5°C. (Based upon EIA-364-56A)	外觀 Appearance	無異狀 No Damage

( ): 參考規格: Reference Standard { }: 參考單位: Reference Unit

<b>A/1</b>	<b>NEW</b>	<b>TITLE:</b> PH2.0mm Pitch Connector Series			<b>Sheet: 6 of 8</b>
<b>REV.</b>	<b>DESCRIPTION</b>	<b>WRITTEN BY:</b> Liu jun	<b>CHECKED BY:</b> K B. Sun	<b>APPROVED BY:</b> Succeed. Sun	<b>DATE: YR/MO/DAY</b> 2017/06/25

**【6. 综合插入力及拔出力 INSERTION/WITHDRAWAL FORCE】 <Connector mating force>**

PIN 數 No. of CKT	插入力(最大值) Insertion (kgf Max.)	拔出力(最小值) Withdrawal (kgf Min.)	PIN 數 No. of CKT	插入力(最大值) Insertion (kgf Max.)	拔出力(最小值) Withdrawal (kgf Min.)
Single	0.7	0.10	9	5.2	1.20
2	2.4	0.50	10	5.6	1.30
3	2.8	0.60	11	6.0	1.40
4	3.2	0.70	12	6.4	1.50
5	3.6	0.80	13	6.8	1.60
6	4.0	0.90	14	7.2	1.80
7	4.4	1.00	15	7.6	1.80
8	4.8	1.10	16	8.0	1.90

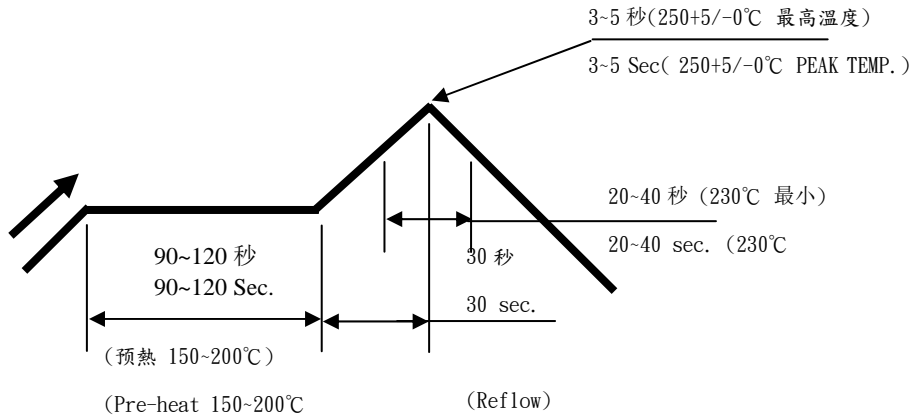
**【7. 端子压著模具尺寸与压著规范 Dimension of die-compaction with terminal and Specification of die-compaction】**

冲模规格 (mm) Die Specification T x W	压著宽度 (mm) 【Die-compaction n width】	压著高度 (mm) 【Die-compaction height】		
		AWG#24	AWG#26	AWG#28
上心: 1.3 x 1.4	1.40~1.50	依端子与线材保持力而定/ Alluding the Retention for Terminal with wire		
下心: 1.4 x 1.4				
上皮: 1.6 x 1.7				
下皮: 1.4 x 1.7				

(端子压著模具尺寸与压著规范供参考用! / Dimension of die-compaction with terminal and Specification of die-compaction Supply Reference!)

<b>A/1</b>	<b>NEW</b>	<b>TITLE:</b> PH2.0mm Pitch Connector Series			<b>Sheet: 7 of 8</b>
<b>REV.</b>	<b>DESCRIPTION</b>	<b>WRITTEN BY:</b> <b>Liu jun</b>	<b>CHECKED BY:</b> <b>K B. Sun</b>	<b>APPROVED BY:</b> <b>Succeed. Sun</b>	<b>DATE: YR/MO/DAY</b> <b>2017/06/25</b>

**【8. SMT 紅外線回流條件 SMT INFRARED REFLOW CONDITION】**



溫度條件曲線圖 / 基板上溫度

TEMPERATURE CONDITION GRAPH / (TEMPERATURE ON BOARD PATTERN SIDE)

注記：由於 P.C 板等焊接裝置改變條件，所以請預先用自己的裝置檢查回流焊的條件。

Notes: Please check the reflow soldering condition by your own devices beforehand. Because the condition changes by the soldering devices, P.C. boards, and so on.

<b>A/1</b>	<b>NEW</b>	<b>TITLE:</b> PH2.0mm Pitch Connector Series			<b>Sheet: 8 of 8</b>
<b>REV.</b>	<b>DESCRIPTION</b>	<b>WRITTEN BY:</b> Liu jun	<b>CHECKED BY:</b> K B. Sun	<b>APPROVED BY:</b> Succeed. Sun	<b>DATE: YR/MO/DAY</b> 2017/06/25